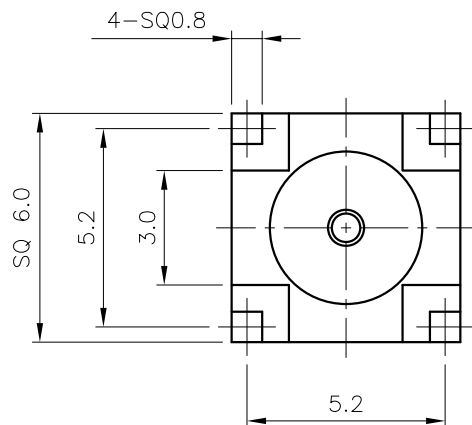
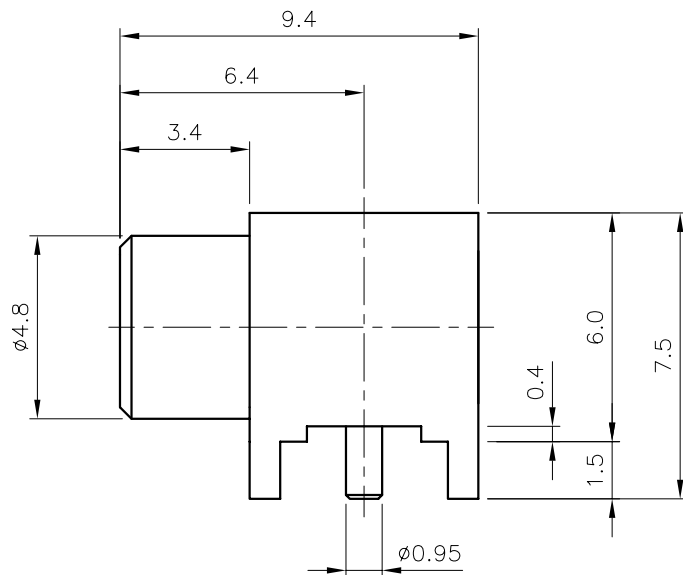
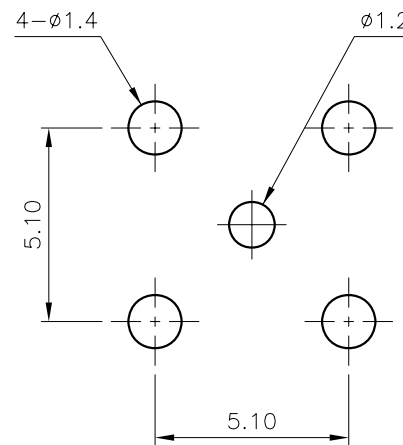




REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	C.K.KIM	I.C.KIM	2001.09.24.
1	[설번No.연구2006-057] 신뢰성 향상 및 조립성 향상 (BODY 치수변경 및 PIN 위치바늘 추가 INSULATOR 구조변경)	I.C.KIM	C.L.CHOI	2006.03.03.
2	[설번No.201604-0004] 냉매방지 및 조립성 개선으로 인한 BODY구조 및 PIN,TEFLON 변경	C.K.KIM	I.C.KIM	2016.04.25.



PCB MOUNTING HOLE

2	1	6	COVER	1	MBsBD C3604BD-F	Gold Plate	DCO00017-5/1
2	1	6	INSULATOR	1	TEFLON		DIN00019-N/1
2	1	5	INSULATOR	1	TEFLON		DIN02759-N/1
2	1	5	INSULATOR	1	TEFLON		DIN00032-N/1
2	1	4	INSULATOR	1	TEFLON		DIN02758-N/1
2	1	4	INSULATOR	1	TEFLON		DIN00030-N/1
2	1	4	CONTACT	1	MBsBD		DCT00020-5/1
2	1	4	CONTACT	1	C3604BD-F	Gold Plate	DCT03678-5/1
2	1	3	CONTACT	1	BeCu C17300	Gold Plate	DCT00026-5/1
2	1	2	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD04156-5/1
2	1	2	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD00085-3/1
2	1	1	사각 BODY	1	MBsBD C3604BD-F	Gold Plate	DBD04148-5/1
2	1	1	사각 BODY	1	MBsBD C3604BD-F	Gold Plate	DBD00054-3/1
		NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 04. 25.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	H.J.LEE	TITLE MCX50 PCB JL-4R
		DRAWN BY	C.K.KIM	
FINISH		SCALE	5/1	DWG NO. CN00050-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	